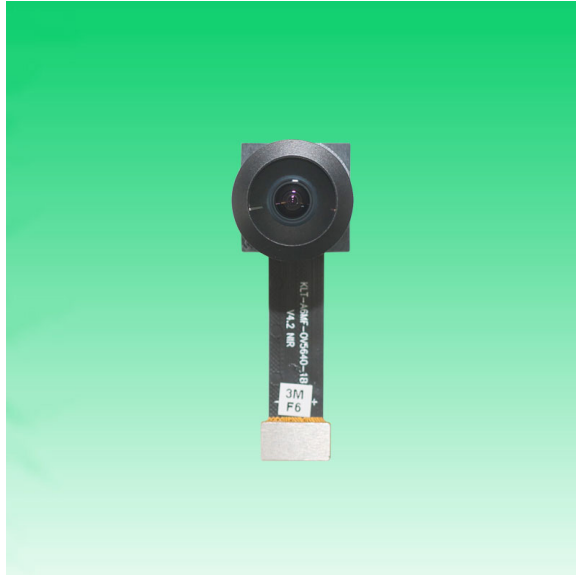


KLT-A6MF-OV5640-1B V4.2 NIR
5MP OmniVision OV5640-1B MIPI Interface M12 No IR
Fixed Focus Camera Module



Front View



Back View

Specifications

Camera Module No.	KLT-A6MF-OV5640-1B V4.2 NIR
Resolution	5MP
Image Sensor	OV5640-1B
Sensor Type	1/4"
Pixel Size	1.4 μm x 1.4 μm
EFL	1.76 mm
F.NO	2.70
Pixel	2592 x 1944
View Angle	162.0°(DFOV) 124.0°(HFOV) 91.0°(VFOV)
Lens Dimensions	13.60 x 13.60 x 17.10 mm
Module Size	40.00 x 13.60 mm
Module Type	Fixed Focus
Interface	MIPI
Auto Focus VCM Driver IC	Embedded
Lens Type	No IR Filter Lens
Operating Temperature	-30°C to +70°C
Mating Connector	AXT524124

KLT-A6MF-OV5640-1B V4.2 NIR
5MP OmniVision OV5640-1B MIPI Interface M12 No IR
Fixed Focus Camera Module



Top View



Side View



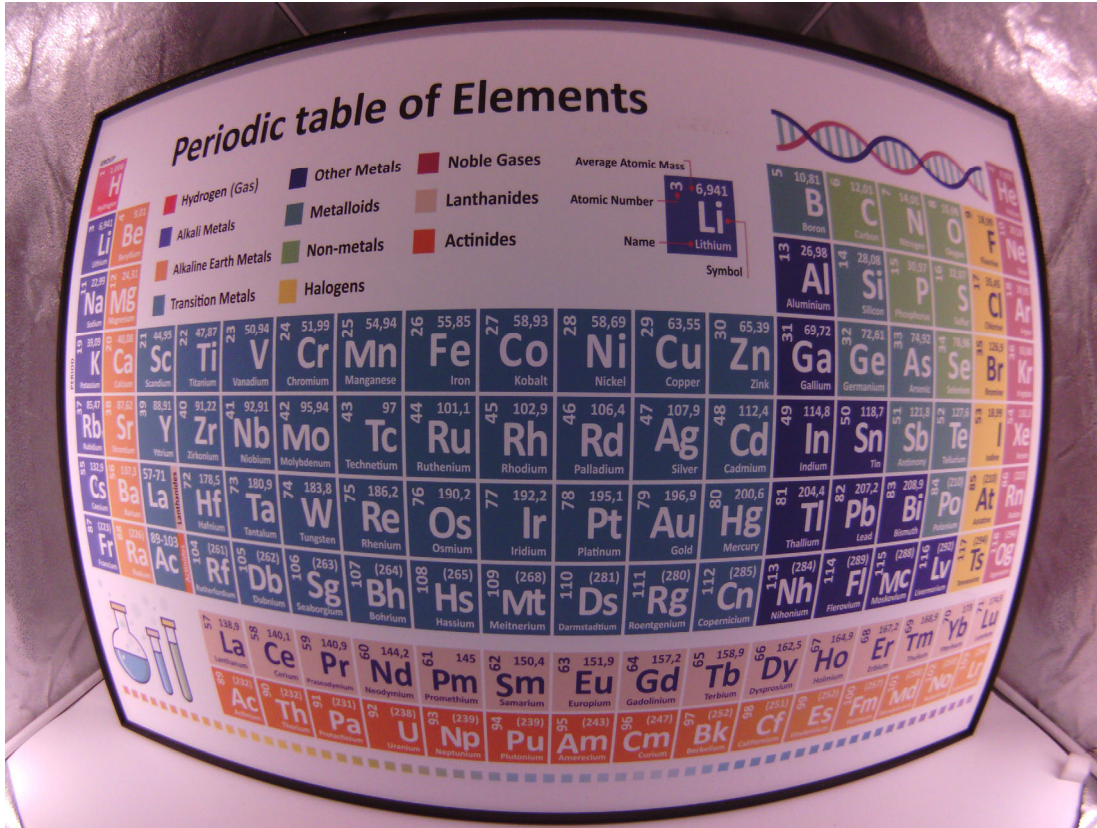
Bottom View



Mating Connector





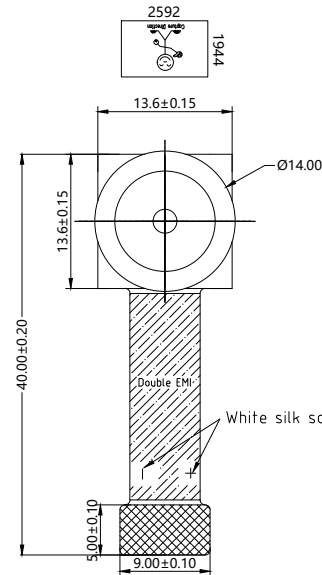


RoHS

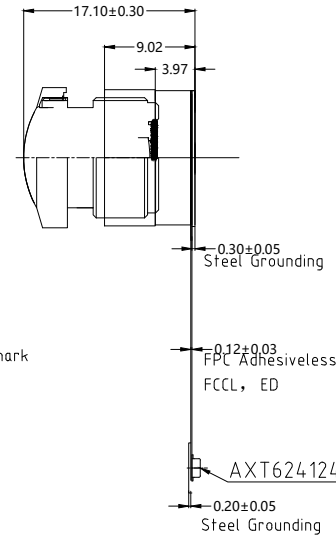
PIN SIGNAL

1	NC
2	AVDD 2.8V
3	SCL
4	SDA
5	RESET
6	PWDN
7	DOVDD 1.8V
8	DVDD 1.5V
9	GND
10	XCLK
11	DGND
12	DGND
13	MDN1
14	MCN
15	MDP1
16	MCP
17	DGND
18	DGND
19	DGND
20	MDN0
21	DGND
22	MDP0
23	DGND
24	DGND

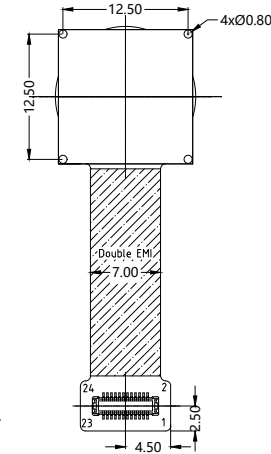
Version	Information
V1.0	First Version
V2.0	Change lens and holder
V4.0	Change FPC length
V4.2	Add Double EMI



TOP VIEW



SIDE VIEW



BOTTOM VIEW

Parameters:

1、Sensor specification:

Image Sensor: OV5640-1B

Pixel: 1.4um*1.4um

Lens Type: 1/4

Important Voltage Description:

DVDD1.5V (external power supply);

2、Lens specification:

FOV: 162°(D);124°(H);91°(V)

F/NO.: 2.7

TV distortion: <17%

Focal length: 1.76mm

Composition: 6G(NO IR FILTER)

Kai Lap Technologies Group Ltd

Designed By

Kevin

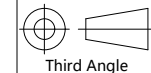
Model Name:

KLT-A6MF-OV5640-1B V4.2 NIR

Checked By

Jacky

Projection Type:



Unit:

mm

Date:

5/26/2025

Scale:

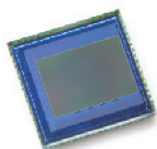
1:1

Sheet:

1 of 1

Version:

1/0



OV5640 5-megapixel product brief



available in
a lead-free
package

1/4-inch, 5-Megapixel SOC Image Sensor Optimized for High-Volume Mobile Markets

The OV5640 delivers a complete 5-megapixel camera solution on a single chip, aimed at offering cost efficiencies that serve the high-volume autofocus (AF) camera phone market. The system-on-a-chip (SOC) sensor features OmniVision's 1.4 micron OmniBSI™ backside illumination architecture to deliver excellent pixel performance and best-in-class low-light sensitivity, while enabling ultra compact camera module designs of 8.5 mm x 8.5 mm with <6 mm z-height. The OV5640 provides the full functionality of a complete camera, including anti-shake technology, AF control, and MIPI while being easier to tune than two-chip solutions, making it an ideal choice in terms of cost, time-to-market and ease of platform integration.

The OV5640 enables 720p HD video at 60 frames per second (fps) and 1080p HD video at 30 fps with complete user control over formatting and output data transfer. The 720p/60 HD video is captured in full field of view (FOV) with 2 x 2 binning, which doubles the sensitivity and improves the signal-to-noise ratio (SNR). Additionally, a unique post-binning re-sampling filter function removes zigzag artifacts around slant edges and minimizes spatial artifacts to deliver even sharper, crisper

color images. To further improve camera performance and user experience, the OV5640 features an internal anti-shake engine for image stabilization, and it supports Scalado™ tagging for faster image preview and zoom.

The OV5640 offers a digital video port (DVP) parallel interface and a high-speed dual lane MIPI interface, supporting multiple output formats. An integrated JPEG compression engine simplifies data transfer for bandwidth-limited interfaces. The sensor's automatic image control functions include automatic exposure control (AEC), automatic white balance (AWB), automatic band filter (ABF), 50/60 Hz automatic luminance detection, and automatic black level calibration (ABLC). The OV5640 delivers programmable controls for frame rate, AEC/AGC 16-zone size/position/weight control, mirror and flip, cropping, windowing, and panning. It also offers color saturation, hue, gamma, sharpness (edge enhancement), lens correction, defective pixel canceling, and noise canceling to improve image quality.

Find out more at www.ovt.com.



applications

- cellular phones
- toys
- PC multimedia
- digital still cameras

ordering information

- **OV05640-A71A-1B** (color, lead-free)
71-pin CSP

features

- 1.4 μm x 1.4 μm pixel with OmniBSI technology for high performance (high sensitivity, low crosstalk, low noise, improved quantum efficiency)
- optical size of 1/4"
- automatic image control functions: automatic exposure control (AEC), automatic white balance (AWB), automatic band filter (ABF), automatic 50/60 Hz luminance detection, and automatic black level calibration (ABLC)
- programmable controls for frame rate, AEC/AGC 16-zone size/position/weight control, mirror and flip, cropping, windowing, and panning
- image quality controls: color saturation, hue, gamma, sharpness (edge enhancement), lens correction, defective pixel canceling, and noise canceling
- support for output formats: RAW RGB, RGB565/555/444, CCIR656, YUV422/420, YCbCr422, and compression
- support for video or snapshot operations
- support for internal and external frame synchronization for frame exposure mode
- support for LED and flash strobe mode
- support for horizontal and vertical sub-sampling, binning
- support for minimizing artifacts on binned image
- support for data compression output
- support for anti-shake
- standard serial SCCB interface
- digital video port (DVP) parallel output interface and dual lane MIPI output interface
- embedded 1.5V regulator for core power
- programmable I/O drive capability, I/O tri-state configurability
- support for black sun cancellation
- support for images sizes: 5 megapixel, and any arbitrary size scaling down from 5 megapixel
- support for auto focus control (AFC) with embedded AF VCM driver
- embedded microcontroller
- suitable for module size of 8.5 x 8.5 x <6mm with both CSP and RW packaging

key specifications (typical)

- **active array size:** 2592 x 1944
- **power supply:**
 - core: 1.425 ~ 1.675V (with embedded 1.5V regulator)
 - analog: 2.6 ~ 3.0V (2.8V typical)
 - I/O: 1.8V / 2.8V
- **power requirements:**
 - active: 140 mA
 - standby: 20 μA
- **temperature range:**
 - operating: -30°C to 70°C junction temperature (see [table 8-2](#))
 - stable image: 0°C to 50°C junction temperature (see [table 8-2](#))
- **output formats:** 8-/10-bit RGB RAW output
- **lens size:** 1/4"
- **lens chief ray angle:** 24° (see [figure 10-2](#))
- **input clock frequency:** 6~27 MHz
- **max S/N ratio:** 36 dB
- **dynamic range:** 68 dB @ 8x gain
- **maximum image transfer rate:**
 - QSXGA (2592x1944): 15 fps
 - 1080p: 30 fps
 - 1280x960: 45 fps
 - 720p: 60 fps
 - VGA (640x480): 90 fps
- **sensitivity:** 600 mV/Lux-sec
- **shutter:** rolling shutter / frame exposure
- **maximum exposure interval:** 1964 x t_{ROW}
- **pixel size:** 1.4 μm x 1.4 μm
- **dark current:** 8 mV/s @ 60°C junction temperature
- **image area:** 3673.6 μm x 2738.4 μm
- **package dimensions:** 5985 μm x 5835 μm



Socket



Header

Compliance with RoHS Directive

NARROW-PITCH, THIN AND SLIM CONNECTOR FOR BOARD-TO-FPC CONNECTION

NARROW PITCH (0.4 mm) CONNECTORS F4S SERIES

FEATURES

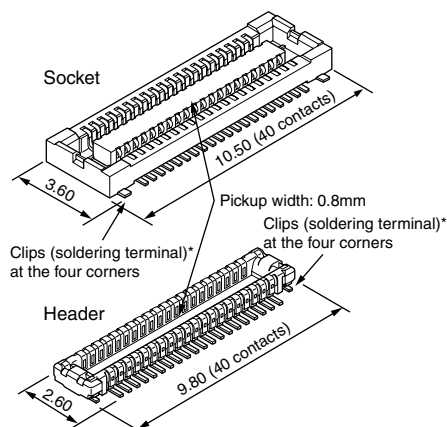
1. Space-saving (3.6 mm widthwise)

The required space is smaller than our F4 series (40-contact type):

Socket — 27% smaller,

Header — 38% smaller

The small size contributes to the miniaturization of target equipment.



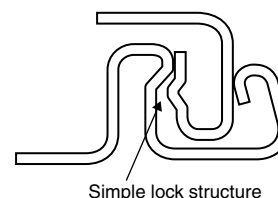
* Clips for preventing the solder joints from being removed

2. Highly reliable

TOUGH CONTACT has strong resistance to adverse environments.

(See Page 6 for details of the structure)
Note: If extra resistance to shock caused by dropping is required, we recommend using our previous F4 Series.

3. The simple lock structure gives tactile feedback that ensures a superior mating/unmating operation feel.



4. Gull-wing type terminals

The gull-wing type terminals facilitate automatic mounting inspections.

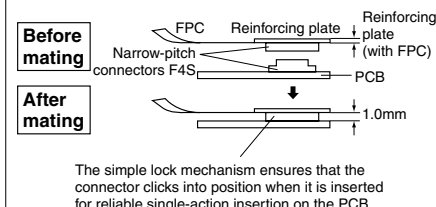
5. Connectors for inspection available

Connectors for inspection are available that are ideal for modular unit inspection and inspection in device assembly processes.

APPLICATIONS

Compact portable devices “Cellular phones, DVC, Digital cameras, etc”

Example of Board-to-FPC connections



The simple lock mechanism ensures that the connector clicks into position when it is inserted for reliable single-action insertion on the PCB.

ORDERING INFORMATION

AXT 4

5: Narrow Pitch Connector F4S (0.4 mm pitch) Socket

6: Narrow Pitch Connector F4S (0.4 mm pitch) Header

Number of contacts (2 digits)

Mated height

<Socket>

1: For mated height 1.0 mm

2: For mated height 1.2 mm

<Header>

1: For mated height 1.0 mm

2: For mated height 1.2 mm

Functions

<Socket, Header>

2: Without positioning bosses

Surface treatment (Contact portion / Terminal portion)

<Socket>

4: Base: Ni plating Surface: Au plating (for Ni barrier available)

<Header>

4: Base: Ni plating Surface: Au plating

Note: Please note that models with a mated height of 1.0 mm (7th digit of part number is “1”) and 1.2 mm (7th digit of part number is “2”) are not compatible.

AXT5, 6

PRODUCT TYPES **TOUGH CONTACT**

Mated height	Number of contacts	Part number		Packing	
		Socket	Header	Inner carton	Outer carton
1.0mm	10	AXT510124	AXT610124	3,000 pieces	6,000 pieces
	12	AXT512124	AXT612124		
	14	AXT514124	AXT614124		
	16	AXT516124	AXT616124		
	18	AXT518124	AXT618124		
	20	AXT520124	AXT620124		
	22	AXT522124	AXT622124		
	24	AXT524124	AXT624124		
	26	AXT526124	AXT626124		
	28	AXT528124	AXT628124		
	30	AXT530124	AXT630124		
	32	AXT532124	AXT632124		
	34	AXT534124	AXT634124		
	36	AXT536124	AXT636124		
	38	AXT538124	AXT638124		
	40	AXT540124	AXT640124		
	42	AXT542124	AXT642124		
	44	AXT544124	AXT644124		
	46	AXT546124	AXT646124		
	48	AXT548124	AXT648124		
	50	AXT550124	AXT650124		
	54	AXT554124	AXT654124		
	60	AXT560124	AXT660124		
	64	AXT564124	AXT664124		
1.2mm	70	AXT570124	AXT670124		
	80	AXT580124	AXT680124		
	10	AXT510224	AXT610224		
	30	AXT530224	AXT630224		
	40	AXT540224	AXT640224		
	50	AXT550224	AXT650224		
	80	AXT580224	AXT680224		

Notes: 1. Order unit: For mass production: in 1-inner-box (1-reel) units
Samples for mounting check: in 50-connector units. Please contact our sales office.
Samples: Small lot orders are possible. Please contact our sales office.
2. The above part numbers are for connectors without positioning bosses, which are standard. When ordering connectors with positioning bosses, please contact our sales office.
3. Please contact us for connectors having a number of contacts other than those listed above.

SPECIFICATIONS

1. Characteristics

	Item	Specifications	Conditions
Electrical characteristics	Rated current	0.3A/contact (Max. 5 A at total contacts)	
	Rated voltage	60V AC/DC	
	Breakdown voltage	150V AC for 1 min.	No short-circuiting or damage at a detection current of 1 mA when the specified voltage is applied for one minute.
	Insulation resistance	Min. 1,000M Ω (initial)	Using 250V DC megger (applied for 1 min.)
	Contact resistance	Max. 90m Ω	Based on the contact resistance measurement method specified by JIS C 5402.
Mechanical characteristics	Composite insertion force	Max. 0.981N/contacts $\times$ contacts (initial)	
	Composite removal force	Min. 0.165N/contacts $\times$ contacts	
	Contact holding force (Socket contact)	Min. 0.49N/contacts	Measuring the maximum force. As the contact is axially pull out.
Environmental characteristics	Ambient temperature	-55°C to +85°C	No freezing at low temperatures. No dew condensation.
	Soldering heat resistance	Peak temperature: 260°C or less (on the surface of the PC board around the connector terminals)	Infrared reflow soldering
		300°C within 5 sec. 350°C within 3 sec.	Soldering iron
	Storage temperature	-55°C to +85°C (product only) -40°C to +50°C (emboss packing)	No freezing at low temperatures. No dew condensation.
	Thermal shock resistance (header and socket mated)	5 cycles, insulation resistance min. 100M Ω , contact resistance max. 90m Ω	Sequence 1. -55 $\frac{3}{4}$ °C, 30 minutes 2. ~, Max. 5 minutes 3. 85 $\frac{3}{4}$ °C, 30 minutes 4. ~, Max. 5 minutes
	Humidity resistance (header and socket mated)	120 hours, insulation resistance min. 100M Ω , contact resistance max. 90m Ω	Bath temperature 40 $\pm$ 2°C, humidity 90 to 95% R.H.
	Saltwater spray resistance (header and socket mated)	24 hours, insulation resistance min. 100M Ω , contact resistance max. 90m Ω	Bath temperature 35 $\pm$ 2°C, saltwater concentration 5 $\pm$ 1%
	H ₂ S resistance (header and socket mated)	48 hours, contact resistance max. 90m Ω	Bath temperature 40 $\pm$ 2°C, gas concentration 3 $\pm$ 1 ppm, humidity 75 to 80% R.H.
Lifetime characteristics	Insertion and removal life	50 times	Repeated insertion and removal speed of max. 200 times/hours
Unit weight		20-contact type: Socket: 0.03 g Header: 0.01 g	

2. Material and surface treatment

Part name	Material	Surface treatment
Molded portion	LCP resin (UL94V-0)	—
Contact and Post	Copper alloy	Contact portion: Base: Ni plating Surface: Au plating Terminal portion: Base: Ni plating Surface: Au plating (except the terminal tips) The socket terminals close to the portion to be soldered have nickel barriers (exposed nickel portions). Metal clips: Sockets: Base: Ni plating Surface: Pd+Au flash plating (except the terminal tips) Headers: Base: Ni plating Surface: Au plating (except the terminal tips)

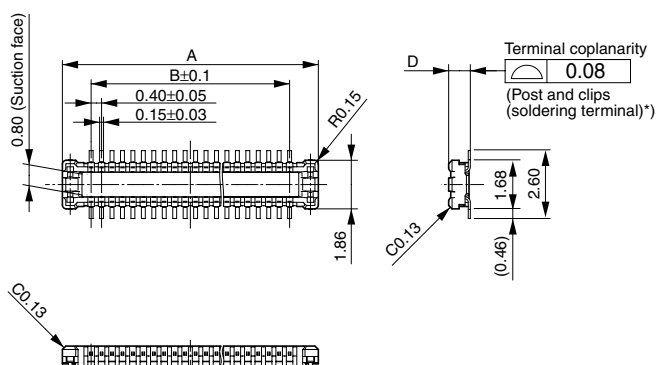
(Unit: mm)

Socket (Mated height: 1.0 mm and 1.2 mm)



Note: Since the clip (soldering terminal)* has a single-piece construction, sections Y and Z are electrically connected.

Number of contacts/ dimension	A	B	C
10	4.5	1.6	3.4
12	4.9	2.0	3.8
14	5.3	2.4	4.2
16	5.7	2.8	4.6
18	6.1	3.2	5.0
20	6.5	3.6	5.4
22	6.9	4.0	5.8
24	7.3	4.4	6.2
26	7.7	4.8	6.6
28	8.1	5.2	7.0
30	8.5	5.6	7.4
32	8.9	6.0	7.8
34	9.3	6.4	8.2
36	9.7	6.8	8.6
38	10.1	7.2	9.0
40	10.5	7.6	9.4
42	10.9	8.0	9.8
44	11.3	8.4	10.2
46	11.7	8.8	10.6
48	12.1	9.2	11.0
50	12.5	9.6	11.4
54	13.3	10.4	12.2
60	14.5	11.6	13.4
64	15.3	12.4	14.2
70	16.5	13.6	15.4
80	18.5	15.6	17.4

CAD Data

Number of contacts/ dimension	A	B	C
10	3.8	1.6	3.2
12	4.2	2.0	3.6
14	4.6	2.4	4.0
16	5.0	2.8	4.4
18	5.4	3.2	4.8
20	5.8	3.6	5.2
22	6.2	4.0	5.6
24	6.6	4.4	6.0
26	7.0	4.8	6.4
28	7.4	5.2	6.8
30	7.8	5.6	7.2
32	8.2	6.0	7.6
34	8.6	6.4	8.0
36	9.0	6.8	8.4
38	9.4	7.2	8.8
40	9.8	7.6	9.2
42	10.2	8.0	9.6
44	10.6	8.4	10.0
46	11.0	8.8	10.4
48	11.4	9.2	10.8
50	11.8	9.6	11.2
54	12.6	10.4	12.0
60	13.8	11.6	13.2
64	14.6	12.4	14.0
70	15.8	13.6	15.2
80	17.8	15.6	17.2

Panasonic Electric Works Automation Controls Business Unit panasonic-electric-works.net/ac

Cameras Applications



Automotive Driver Pilot



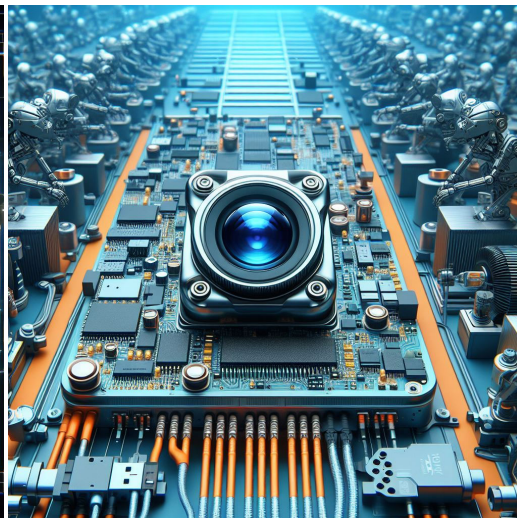
Live Streaming



Video Conference



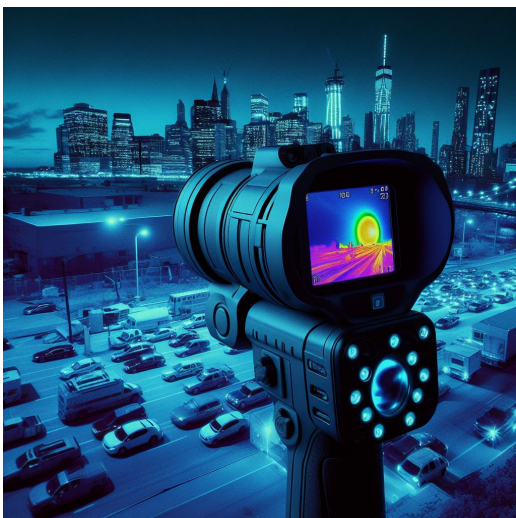
Eye Tracker Biometric Detection



Machine Vision



Agricultural Monitor



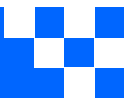
Night Vision Security



Drone and Sports Eagle Eyes



Interactive Pet Camera



Cameras Applications

your BEST camera module partner



IMAGING DEVICES



Camera Module Pinout Definition Reference Chart

OmniVision Sony Samsung On-Semi Aptina Himax GalaxyCore PixArt SmartSens Sensors	
Pin Signal	Description
DGND GND	ground for digital circuit
AGND	ground for analog circuit
PCLK DCK	DVP PCLK output
XCLR PWDN XSHUTDOWN STANDBY	power down active high with internal pull-down resistor
MCLK XVCLK XCLK INCK	system input clock
RESET RST	reset active low with internal pull-up resistor
NC NULL	no connect
SDA SIO_D SIOD	SCCB data
SCL SIO_C SIOC	SCCB input clock
VSYNC XVS FSYNC	DVP VSYNC output
HREF XHS	DVP HREF output
DOVDD	power for I/O circuit
AFVDD	power for VCM circuit
AVDD	power for analog circuit
DVDD	power for digital circuit
STROBE FSTROBE	strobe output
FSIN	synchronize the VSYNC signal from the other sensor
SID	SCCB last bit ID input
ILPWM	mechanical shutter output indicator
FREX	frame exposure / mechanical shutter
GPIO	general purpose inputs
SLASEL	I2C slave address select
AFEN	CEN chip enable active high on VCM driver IC
MIPI Interface	
MDN0 DN0 MD0N DATA_N DMO1N	MIPI 1st data lane negative output
MDP0 DP0 MD0P DATA_P DMO1P	MIPI 1st data lane positive output
MDN1 DN1 MD1N DATA2_N DMO2N	MIPI 2nd data lane negative output
MDP1 DP1 MD1P DATA2_P DMO2P	MIPI 2nd data lane positive output
MDN2 DN2 MD2N DATA3_N DMO3N	MIPI 3rd data lane negative output
MDP2 DP2 MD2P DATA3_P DMO3P	MIPI 3rd data lane positive output
MDN3 DN3 MD3N DATA4_N DMO4N	MIPI 4th data lane negative output
MDP3 DP3 MD3P DATA4_P DMO4P	MIPI 4th data lane positive output
MCN CLKN CLK_N DCKN	MIPI clock negative output
MCP CLKP MCP CLK_P DCKN	MIPI clock positive output
DVP Parallel Interface	
D0 DO0 Y0	DVP data output port 0
D1 DO1 Y1	DVP data output port 1
D2 DO2 Y2	DVP data output port 2
D3 DO3 Y3	DVP data output port 3
D4 DO4 Y4	DVP data output port 4
D5 DO5 Y5	DVP data output port 5
D6 DO6 Y6	DVP data output port 6
D7 DO7 Y7	DVP data output port 7
D8 DO8 Y8	DVP data output port 8
D9 DO9 Y9	DVP data output port 9
D10 DO10 Y10	DVP data output port 10
D11 DO11 Y11	DVP data output port 11

Camera Reliability Test

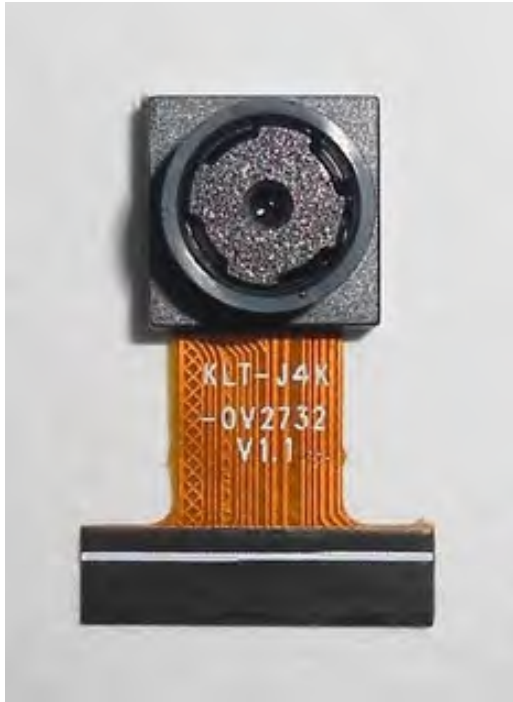
Reliability Inspection Item			Testing Method	Acceptance Criteria
Category		Item		
Environmental	Storage Temperature	High 60°C 96 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 96 Hours	Temperature Chamber	No Abnormal Situation
	Operation Temperature	High 60°C 24 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 24 Hours	Temperature Chamber	No Abnormal Situation
	Humidity	60°C 80% 24 Hours	Temperature Chamber	No Abnormal Situation
	Thermal Shock	High 60°C 0.5 Hours Low -20°C 0.5 Hours Cycling in 24 Hours	Temperature Chamber	No Abnormal Situation
Physical	Drop Test (Free Falling)	Without Package 60cm	10 Times on Wood Floor	Electrically Functional
		With Package 60cm	10 Times on Wood Floor	Electrically Functional
	Vibration Test	50Hz X-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Y-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Z-Axis 2mm 30min	Vibration Table	Electrically Functional
	Cable Tensile Strength Test	Loading Weight 4 kg 60 Seconds Cycling in 24 Hours	Tensile Testing Machine	Electrically Functional
Electrical	ESD Test	Contact Discharge 2 KV	ESD Testing Machine	Electrically Functional
		Air Discharge 4 KV	ESD Testing Machine	Electrically Functional
	Aging Test	On/Off 30 Seconds Cycling in 24 Hours	Power Switch	Electrically Functional
	USB Connector	On/Off 250 Times	Plug and Unplug	Electrically Functional



Inspection Item			Inspection Method	Standard of Inspection
Category		Item		
Appearance	FPC/ PCB	Color	The Naked Eye	Major Difference is Not Allowed.
		Be Torn/Chopped	The Naked Eye	Copper Crack Exposure is Not Allowed.
		Marking	The Naked Eye	Clear, Recognizable (Within 30cm Distance)
	Holder	Scratches	The Naked Eye	The Inside Crack Exposure is Not Allowed
		Gap	The Naked Eye	Meet the Height Standard
		Screw	The Naked Eye	Make Sure Screws Are Presented (If Any)
		Damage	The Naked Eye	The Inside Crack Exposure is Not Allowed
	Lens	Scratch	The Naked Eye	No Effect On Resolution Standard
		Contamination	The Naked Eye	No Effect On Resolution Standard
		Oil Film	The Naked Eye	No Effect On Resolution Standard
		Cover Tape	The Naked Eye	No Issue On Appearance.
	Function	Image	No Communication	Test Board
Bright Pixel			Black Board	Not Allowed In the Image Center
Dark Pixel			White board	Not Allowed In the Image Center
Blurry			The Naked Eye	Not Allowed
No Image			The Naked Eye	Not Allowed
Vertical Line			The Naked Eye	Not Allowed
Horizontal Line			The Naked Eye	Not Allowed
Light Leakage			The Naked Eye	Not Allowed
Blinking Image			The Naked Eye	Not Allowed
Bruise			Inspection Jig	Not Allowed
Resolution			Chart	Follows Outgoing Inspection Chart Standard
Color			The Naked Eye	No Issue
Noise			The Naked Eye	Not Allowed
Corner Dark			The Naked Eye	Less Than 100px By 100px
Color Resolution			The Naked Eye	No Issue
Dimension			Height	The Naked Eye
	Width	The Naked Eye	Follows Approval Data Sheet	
	Length	The Naked Eye	Follows Approval Data Sheet	
	Overall	The Naked Eye	Follows Approval Data Sheet	

KLT Package Solutions

KLT Camera Module



Complete with Lens Protection Film



Tray with Grid and Space

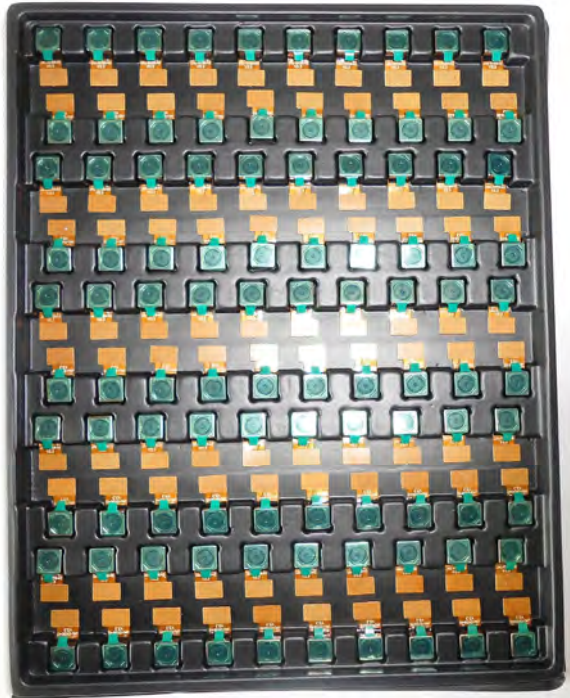


Place Cameras on the Tray



Camera Modules Package Solution

Full Tray of Cameras



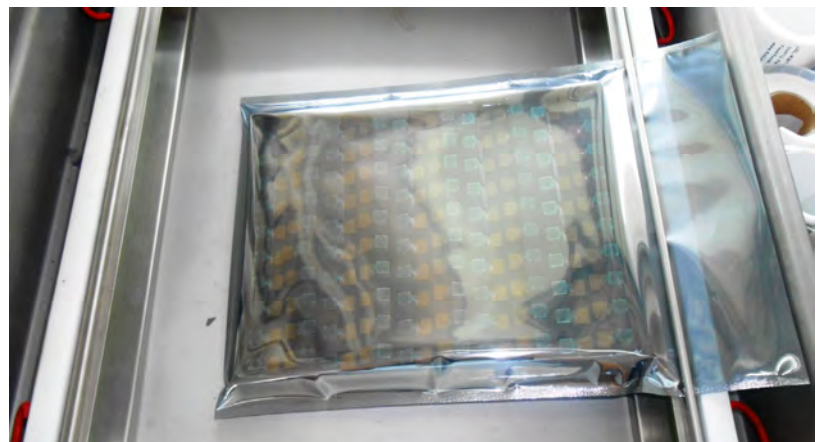
Cover Tray with Lid



Put Tray into Anti-Static Bag



Vacuum the Anti-Static Bag



Camera Modules Package Solution

Sealed Vacuum Bag with Labels

1. Model and Description 2. Quantity 3. Shipping Date 4. Caution



Large Order Package Solution

Place Foam Sheets Between Trays



Foam Sheets are Slightly Larger than Trays



Place Foam Sheets and Trays into Box

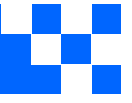


Foam Sheets are Tightly Fitting Box





CMOS CAMERA MODULES



*your **BEST** camera module partner*

Small Order Package Solution

Place Foam Sheets and Trays into Small Box



Foam Sheets are Nicely Fitting the Small Box



Package in Small Box for Shipment



Place Small Boxes into Larger Box



www.KaiLapTech.com sales@KaiLapTech.com Tel: (852) 6908 1256 Fax: (852) 3017 6778

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Carbon Box Package Solution

Seal the Carbon Box

Final Package Labelled Box



Carbon Box Ready for Shipment

1. Delivery Address and Phone No. 2. Box No. and Ship Date 3. Fragile Caution



Sample Order Package Solution

Place Sample into Small Anti-Static Bag



Place Connectors into Small Ant-Static Bag



Sample Labels on the Small Bag

1. Camera Module or Connector Model 2. Shipping Date and Quantity 3. Caution



Connectors Large Order Package Solution

Connectors in a Wheel



Label Connectors in the Wheel

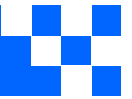


The Wheel is Perfectly Fitting the Box



Connectors Box Ready for Shipment

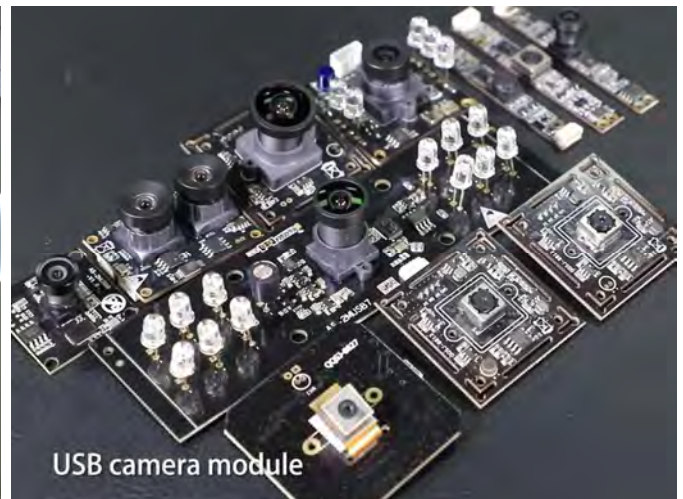


**Company Kai Lap Technologies (KLT)**

Kai Lap Technologies Group Limited. (KLT) was established in 2009, a next-generation technology driven manufacturer specialized in research, design, and produce of audio and video products. KLT is occupying 20,000 square feet automated plants with 100 employees of annual throughput 30,000,000 units cameras.

KLT provides OEM, ODM design, contract manufacturing, and builds the camera products. You may provide the requirements to us, even with a hand draft, our sales and engineering work together to meet your needs. We consider ourselves your last-term partner in developing practical and innovative solutions.

Our team covers everything from initial concept development to mass produced product. KLT specializes in customized camera design, raw material, electronic engineering, firmware/software development, product testing, and packing design. Our experienced strategic supply systems offer a robust and dependable manufacturing capacity for orders of various sizes.

**Limited Warranty**

KLT provides the following limited warranty if you purchased the Product(s) directly from KLT company or from KLT's website, www.KaiLapTech.com. Product(s) purchased from other sellers or sources are not covered by this Limited Warranty. KLT guarantees that the Product(s) will be free from defects in materials and workmanship under normal use for a period of one (1) year from the date you receive the product ("Warranty Period").

For all Product(s) that contain or develop material defects in materials or workmanship during the Warranty Period, KLT will, at its sole option, either: (i) repair the Product(s); (ii) replace the Product(s) with a new or refurbished Product(s) (replacement Product(s) being of identical model or functional equivalent); or (iii) provide you a refund of the price you paid for the Product(s).

This Limited Warranty of KLT is solely limited to repair and/or replacement on the terms set forth above. KLT is not reliable or responsible for any subsequent events.





CMOS CAMERA MODULES



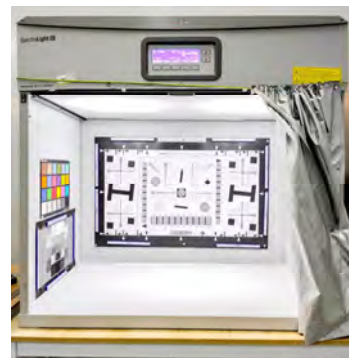
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KLT Strength

Powerful Factory



Professional Service



Promised Delivery



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